

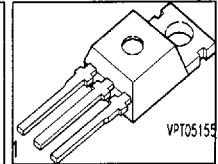
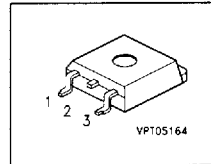
SIPMOS® Power Transistor

Features

- N channel
- Enhancement mode
- Avalanche rated
- Logic Level
- dv/dt rated
- 175°C operating temperature

Product Summary

Drain source voltage	V_{DS}	55	V
Drain-Source on-state resistance	$R_{DS(on)}$	0.04	Ω
Continuous drain current	I_D	20	A



Type	Package	Ordering Code	Packaging
BUZ101SL	P-TO220-3-1	Q67040-S4012-A2	Tube
BUZ101SL E3045A	P-TO263-3-2	Q67040-S4012-A6	Tape and Reel
BUZ101SL E3045	P-TO263-3-2	Q67040-S4012-A5	Tube

Pin 1	Pin 2	Pin 3
G	D	S

Maximum Ratings, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_D	20 14	A
Pulsed drain current $T_C = 25^\circ\text{C}$	I_{Dpulse}	80	
Avalanche energy, single pulse $I_D = 20\text{ A}$, $V_{DD} = 25\text{ V}$, $R_{GS} = 25\ \Omega$	E_{AS}	90	mJ
Avalanche energy, periodic limited by T_{jmax}	E_{AR}	5.5	
Reverse diode dv/dt $I_S = 20\text{ A}$, $V_{DS} = 40\text{ V}$, $di/dt = 200\text{ A}/\mu\text{s}$, $T_{jmax} = 175^\circ\text{C}$	dv/dt	6	kV/ μs
Gate source voltage	V_{GS}	± 20	V
Power dissipation $T_C = 25^\circ\text{C}$	P_{tot}	55	W
Operating and storage temperature	T_j, T_{stg}	-55... +175	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1		55/175/56	

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Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	-	2.7	K/W
Thermal resistance, junction - ambient, leded	R_{thJA}	-	-	62	
SMD version, device on PCB:	R_{thJA}				
@ min. footprint		-	-	62	
@ 6 cm ² cooling area ¹⁾		-	-	40	

Electrical Characteristics, at $T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain- source breakdown voltage $V_{GS} = 0\text{ V}$, $I_D = 0.25\text{ mA}$	$V_{(BR)DSS}$	55	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D = 40\text{ }\mu\text{A}$	$V_{GS(th)}$	1.2	1.6	2	
Zero gate voltage drain current $V_{DS} = 50\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 25\text{ }^{\circ}\text{C}$ $V_{DS} = 50\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 150\text{ }^{\circ}\text{C}$	I_{DSS}	-	0.1	1	μA
		-	-	100	
Gate-source leakage current $V_{GS} = 20\text{ V}$, $V_{DS} = 0\text{ V}$	I_{GSS}	-	10	100	nA
Drain-Source on-state resistance $V_{GS} = 4.5\text{ V}$, $I_D = 14\text{ A}$ $V_{GS} = 10\text{ V}$, $I_D = 14\text{ A}$	$R_{DS(on)}$	-	0.057	0.07	Ω
		-	0.034	0.04	

¹ Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at $T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Transconductance $V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$, $I_D = 14\text{ A}$	g_{fs}	7	14	-	S
Input capacitance $V_{GS} = 0\text{ V}$, $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	C_{iss}	-	560	700	pF
Output capacitance $V_{GS} = 0\text{ V}$, $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	C_{oss}	-	170	215	
Reverse transfer capacitance $V_{GS} = 0\text{ V}$, $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	C_{rss}	-	95	120	
Turn-on delay time $V_{DD} = 30\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 20\text{ A}$, $R_G = 10\text{ }\Omega$	$t_{d(on)}$	-	15	25	ns
Rise time $V_{DD} = 30\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 20\text{ A}$, $R_G = 10\text{ }\Omega$	t_r	-	35	55	
Turn-off delay time $V_{DD} = 30\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 20\text{ A}$, $R_G = 10\text{ }\Omega$	$t_{d(off)}$	-	15	25	
Fall time $V_{DD} = 30\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 20\text{ A}$, $R_G = 10\text{ }\Omega$	t_f	-	15	25	

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Electrical Characteristics, at $T_j = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Gate to source charge $V_{DD} = 40\text{ V}$, $I_D = 20\text{ A}$	Q_{gs}	-	3	4.5	nC
Gate to drain charge $V_{DD} = 40\text{ V}$, $I_D = 20\text{ A}$	Q_{gd}	-	10	15	
Gate charge total $V_{DD} = 40\text{ V}$, $I_D = 20\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$	Q_g	-	24	36	
Gate plateau voltage $V_{DD} = 40\text{ V}$, $I_D = 20\text{ A}$	$V_{(\text{plateau})}$	-	4.06	-	V

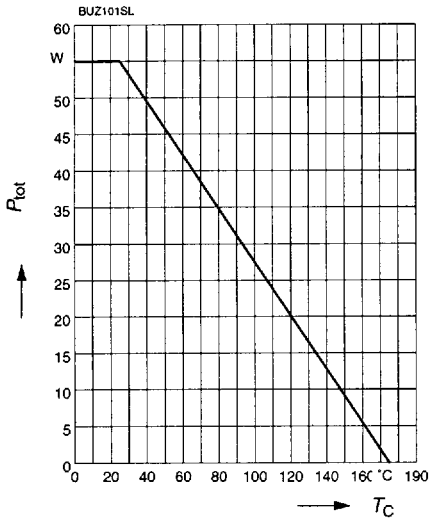
Reverse Diode

Inverse diode continuous forward current $T_C = 25\text{ }^{\circ}\text{C}$	I_S	-	-	20	A
Inverse diode direct current,pulsed $T_C = 25\text{ }^{\circ}\text{C}$	I_{SM}	-	-	80	
Inverse diode forward voltage $V_{GS} = 0\text{ V}$, $I_F = 40\text{ A}$	V_{SD}	-	1.12	1.8	V
Reverse recovery time $V_R = 30\text{ V}$, $I_F = I_S$, $di_F/dt = 100\text{ A}/\mu\text{s}$	t_{rr}	-	50	75	ns
Reverse recovery charge $V_R = 30\text{ V}$, $I_F = I_S$, $di_F/dt = 100\text{ A}/\mu\text{s}$	Q_{rr}	-	0.12	0.18	μC

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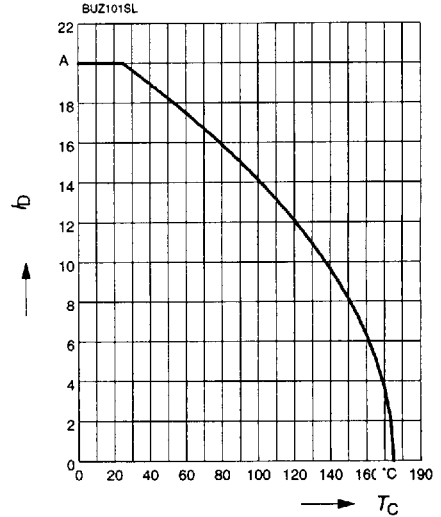
Power Dissipation

$$P_{\text{tot}} = f(T_C)$$


Drain current

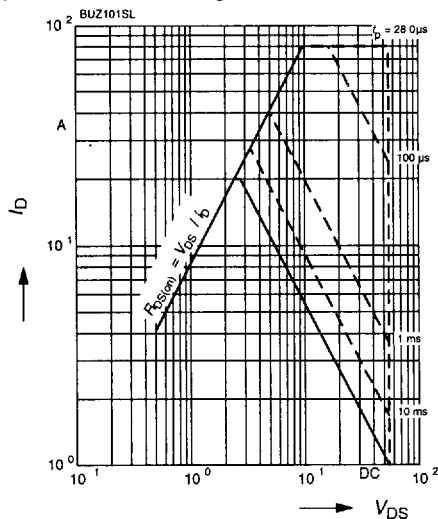
$$I_D = f(T_C)$$

parameter: $V_{GS} \geq 10 \text{ V}$


Safe operating area

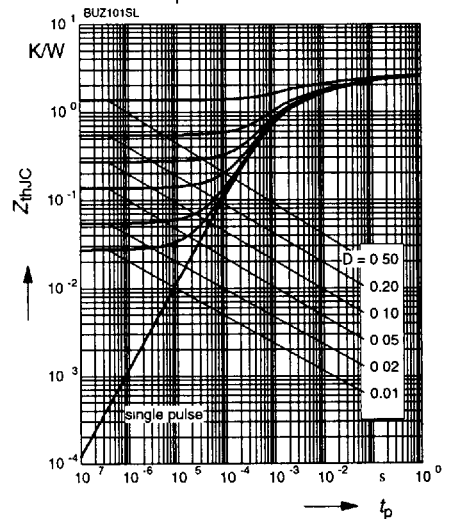
$$I_D = f(V_{DS})$$

parameter: $D = 0$, $T_C = 25^\circ\text{C}$


Transient thermal impedance

$$Z_{thJC} = f(t_p)$$

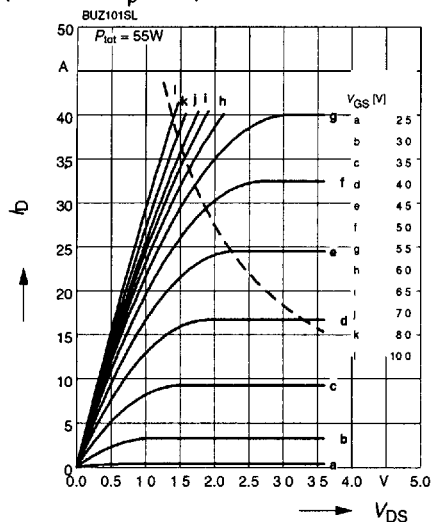
parameter: $D = t_p / T$



Typ. output characteristics

$$I_D = f(V_{DS})$$

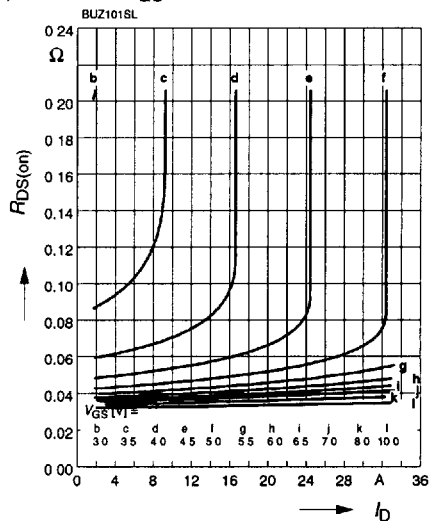
parameter: $t_p = 80 \mu s$



Typ. drain-source-on-resistance

$$R_{DS(on)} = f(I_D)$$

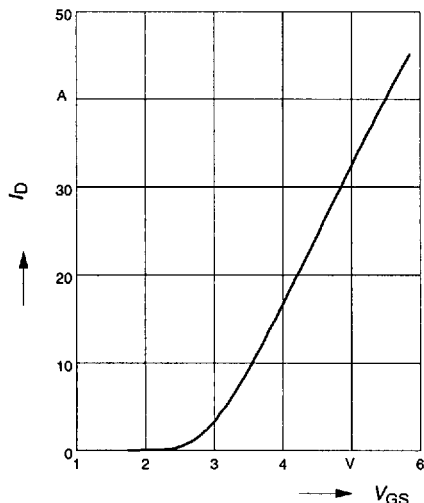
parameter: V_{GS}



Typ. transfer characteristics $I_D = f(V_{GS})$

parameter: $t_p = 80 \mu s$

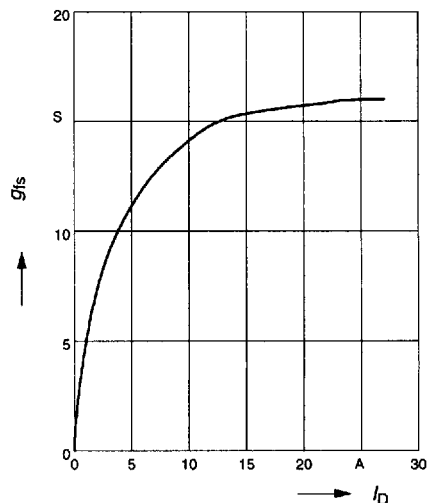
$$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$



Typ. forward transconductance

$$g_{fs} = f(I_D); T_j = 25^\circ C$$

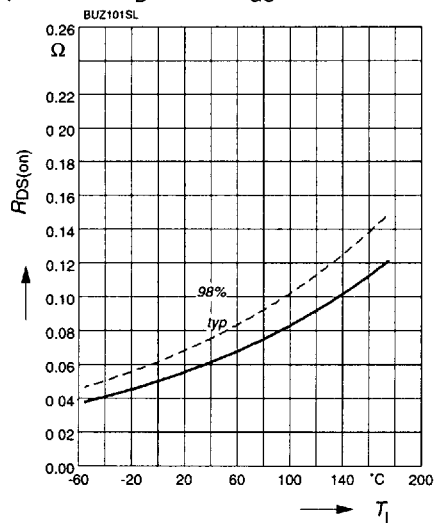
parameter: g_{fs}



Drain-source on-resistance

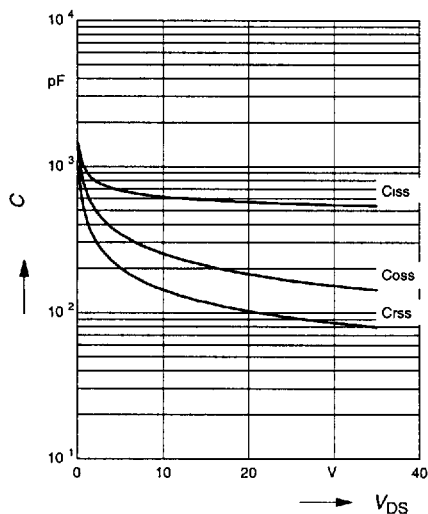
$$R_{DS(on)} = f(T_J)$$

parameter: $I_D = 14\text{ A}$, $V_{GS} = 4.5\text{ V}$


Typ. capacitances

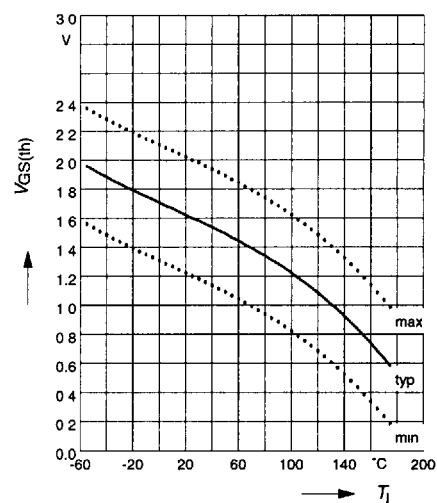
$$C = f(V_{DS})$$

parameter: $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$


Gate threshold voltage

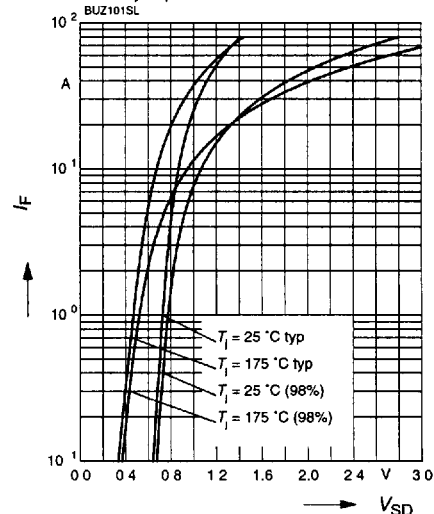
$$V_{GS(th)} = f(T_J)$$

parameter: $V_{GS} = V_{DS}$, $I_D = 40\text{ }\mu\text{A}$

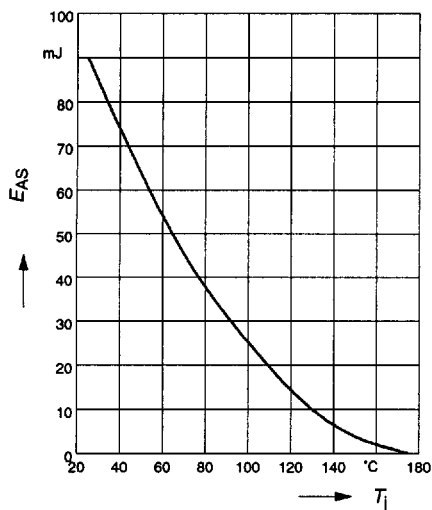

Forward characteristics of reverse diode

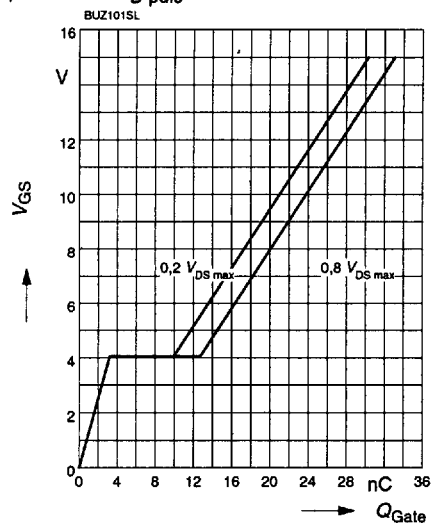
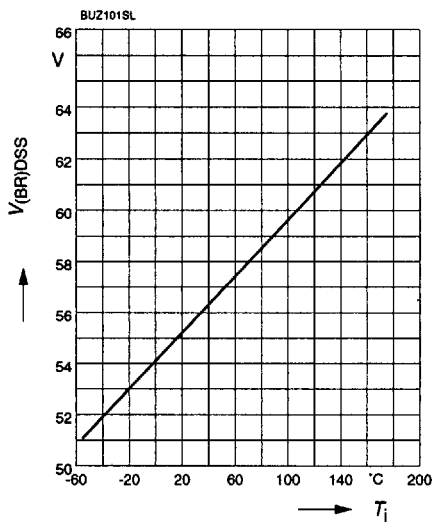
$$I_F = f(V_{SD})$$

parameter: $T_J = T_p = 80\text{ }\mu\text{s}$



Avalanche Energy $E_{AS} = f(T_j)$

 parameter: $I_D = 20\text{ A}$, $V_{DD} = 25\text{ V}$
 $R_{GS} = 25\ \Omega$

Typ. gate charge
 $V_{GS} = f(Q_{Gate})$

 parameter: $I_D\text{ puls} = 20\text{ A}$

Drain-source breakdown voltage
 $V_{(BR)DSS} = f(T_j)$


Gehäusemaßbilder

(Maße in mm, wenn nicht anders angegeben)

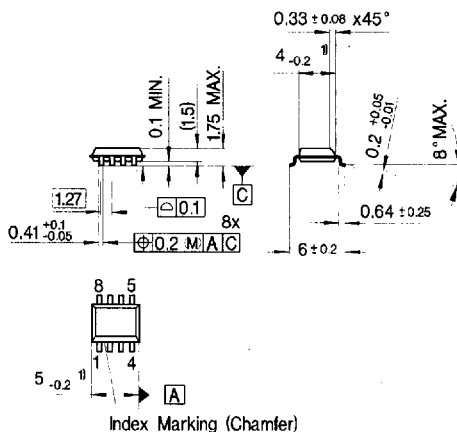
Package Outlines

(Dimensions in mm, unless otherwise specified)

P-DSO-8-6/-7

Gewicht etwa 0.15 g

Approx. weight 0.15 g



1) Does not include plastic or metal protrusion of 0.15 max. per side

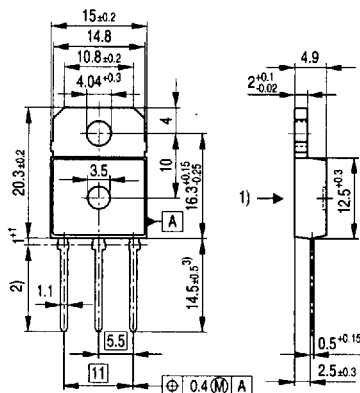
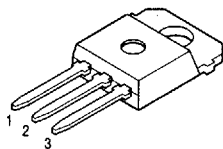
Bild 16

Figure 16

P-T0218-AA (P-T0218-2-1)

Gewicht etwa 4.9 g

Approx. weight 4.9 g



- 1) Punch direction, burr max. 0.04
- 2) Dip tinning
- 3) Max. 15.5 by dip tinning
press burr max. 0.05
radii not dimensioned max. 0.2

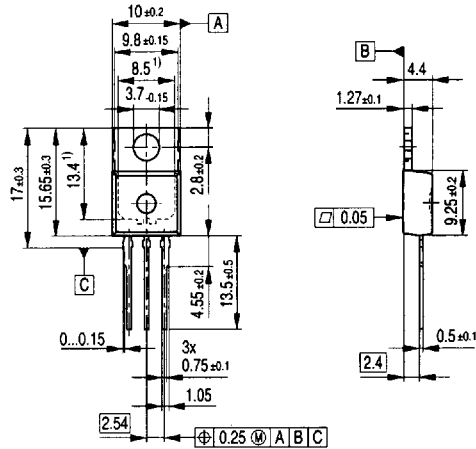
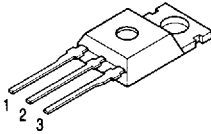
GPT05156

Bild 17

Figure 17

P-TO220-3-1

Gewicht etwa 1.8 g
Approx. weight 1.8 g



¹⁾ Typical

All metal surfaces tin plated, except area of cut.

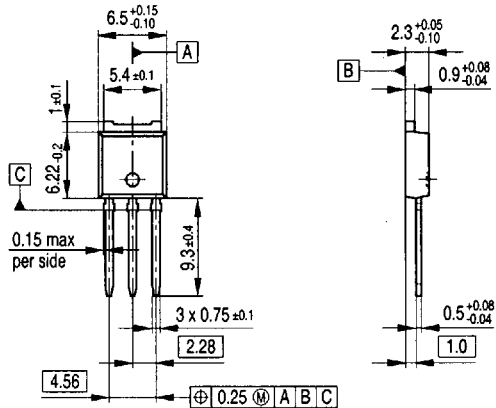
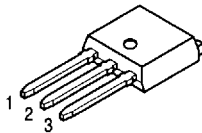
GPT05155

Bild 18

Figure 18

P-TO251-3-1

Gewicht etwa 2.0 g
Approx. weight 2.0 g



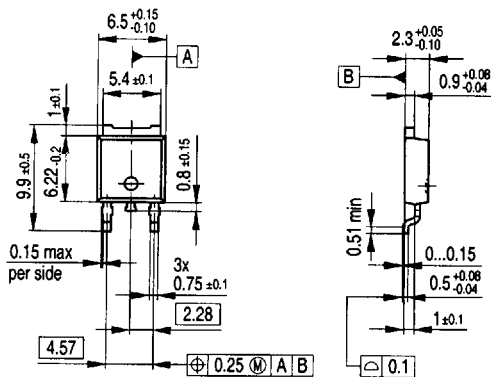
All metal surfaces tin plated, except area of cut.

GPT09060

Bild 19

Figure 19

Gewicht etwa 0.38 g
Approx. weight 0.38 g



GPT09051

Figure 20

Technical drawing of a mechanical part, showing two views: a front view (left) and a side view (right). The drawing includes dimensions and tolerances.

Front View (Left):

- Overall width: 10 ± 0.2
- Inner width: 8.5^{+1}_{-0}
- Top flange thickness: 1 ± 0.3
- Overall height: 11.6 ± 0.3
- Internal height: 8^{+1}_{-0}
- Bottom flange thickness: 4.55 ± 0.2
- Overall height including bottom flange: 13.5 ± 0.5
- Bottom flange width: $3 \times 0.75 \pm 0.1$
- Bottom flange thickness: 1.05 ± 0.2
- Bottom flange width: 2×2.54
- Feature A: A square feature on the top flange.
- Feature B: A square feature on the top flange.
- Feature C: A square feature on the bottom flange.

Side View (Right):

- Overall width: 4.4 ± 0.1
- Internal width: 1.27 ± 0.1
- Overall height: 9.25 ± 0.2
- Internal height: 0.5 ± 0.1
- Bottom flange thickness: 2.4
- Feature A: A square feature on the top flange.
- Feature B: A square feature on the top flange.
- Feature C: A square feature on the bottom flange.

Feature A: A square feature with a width of 0.25 and a height of 0.25 .

Feature B: A square feature with a width of 0.05 and a height of 0.05 .

Feature C: A square feature with a width of 0.05 and a height of 0.05 .

All metal surfaces tin plated, except area of cut.

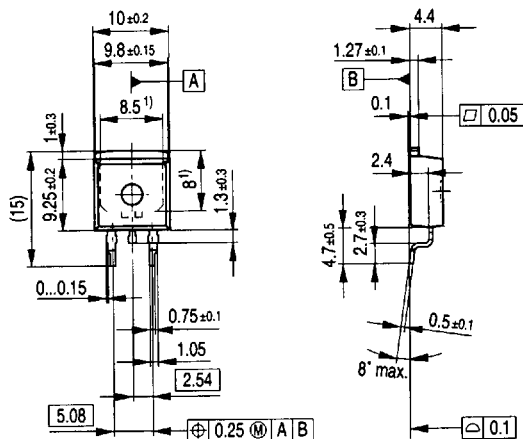
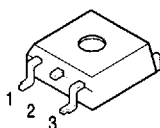
GPT09244

Figure 21

P-TO263-3-2/D²PAK

Gewicht etwa 1.38 g

Approx. weight 1.38 g



¹⁾ Typical

All metal surfaces tin plated, except area of cut.

GPT09085

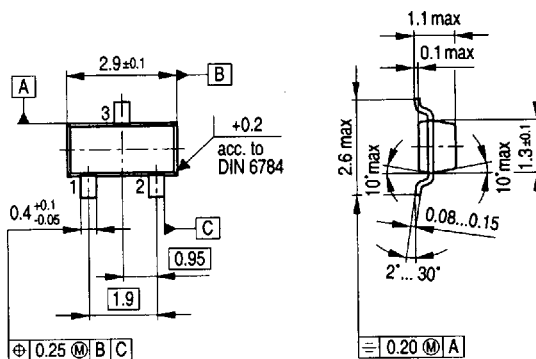
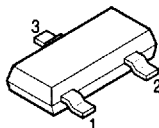
Bild 22

Figure 22

SOT-23 (P-SOT23-3-1)

Gewicht etwa 0.01 g

Approx. weight 0.01 g



GPS05557

Bild 23

Figure 23

Gewicht etwa 0.01 g
Approx. weight 0.01 g



Figure 24

Gewicht etwa 0.15 g
Approx. weight 0.15 g



Figure 25

TO-92

Gewicht etwa 0.23 g

Approx. weight 0.23 g

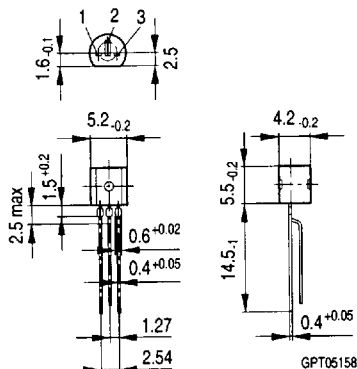
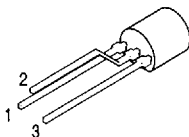


Bild 26

Figure 26

TO-92-E6288

Gewicht etwa 0.23 g

Approx. weight 0.23 g

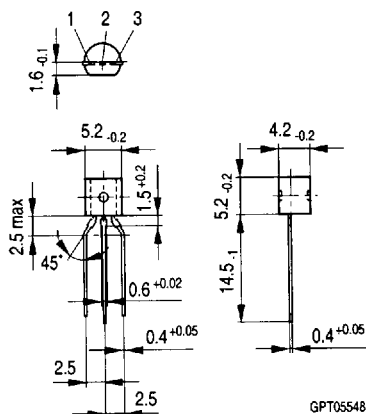
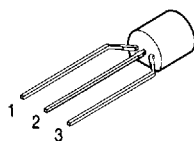


Bild 27

Figure 27

Sorts of Packing

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

SMD = Surface Mounted Device